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**REMARKS**

The Applicant would like to thank the Examiner for the recognition of the allowable subject matter. The Applicant has respectfully postponed re-writing the allowable claims into independent form as the Applicant believes there is sufficient grounds for traversal of the rejected underlying claims.

**Claims 1, 6-7, 10-11 and 15-16 rejected under 35 USC 102(b)**

The basis of the Examiner's rejection of the aforementioned claims is based on an anticipation argument regarding Goldberg et al (US 5,317,879). The Examiner asserts that the Goldberg reference teaches all the underlying limitations of the aforementioned claims. The Applicant respectfully traverses this rejection and seeks reconsideration.

Reviewing the present Application in comparison to the Goldberg reference:

**The present invention claims**

A coldhead sleeve 52 connected to a cooler block 64 by a plurality of braid elements 60.

A highly thermally conductive block 66 positioned between the cooler block 64 and an outer thermal shield 50.

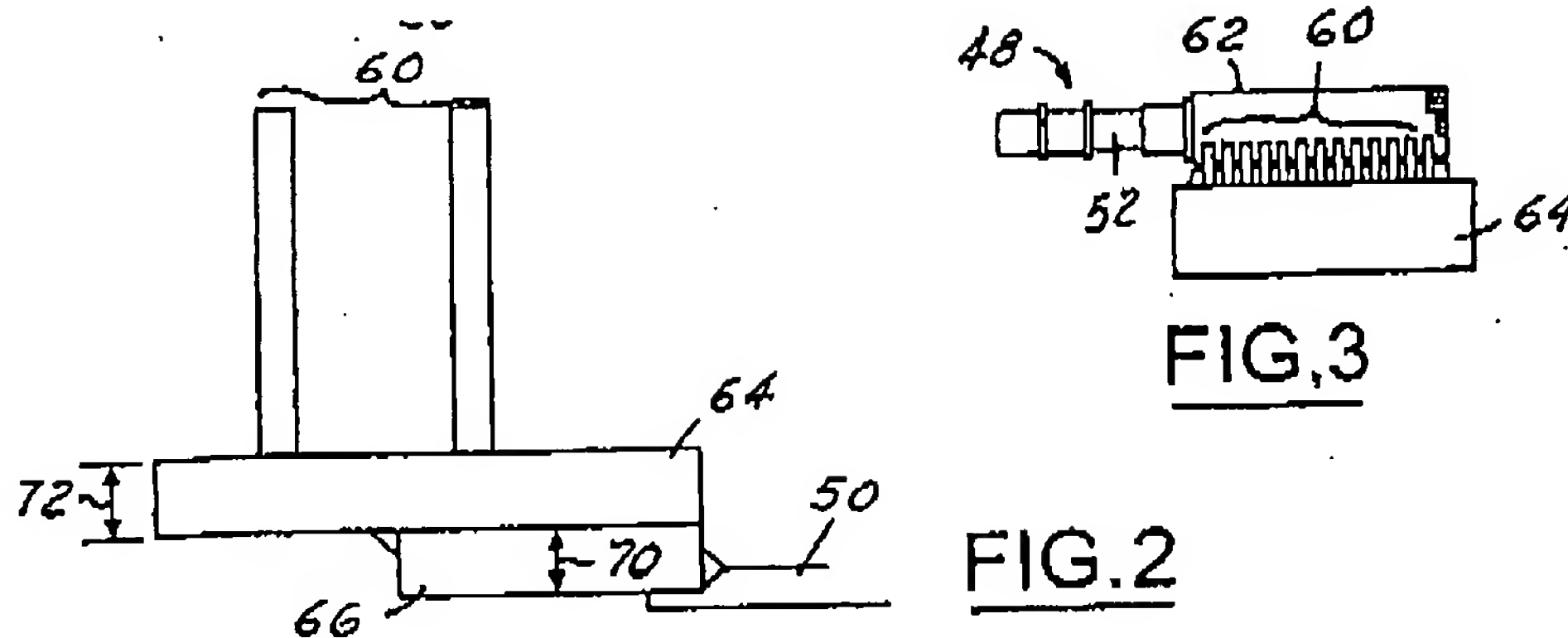
(Additional limitations are contained within but are not required to disqualify Goldberg as a reference.)

Thus the present application claims braids running into a cooler block and an ADDITIONAL highly thermally conductive block 66 between the cooler block 64 and the outer thermal shield 50.

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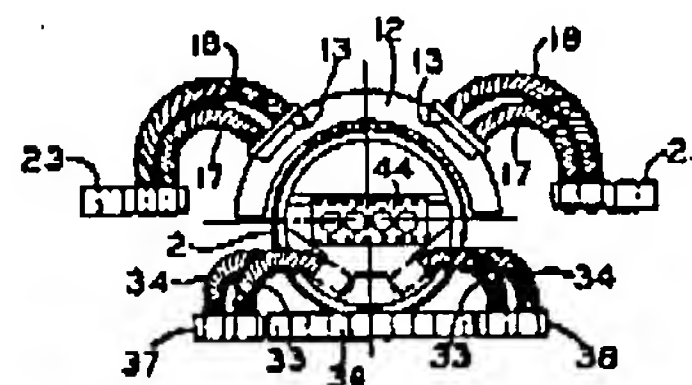
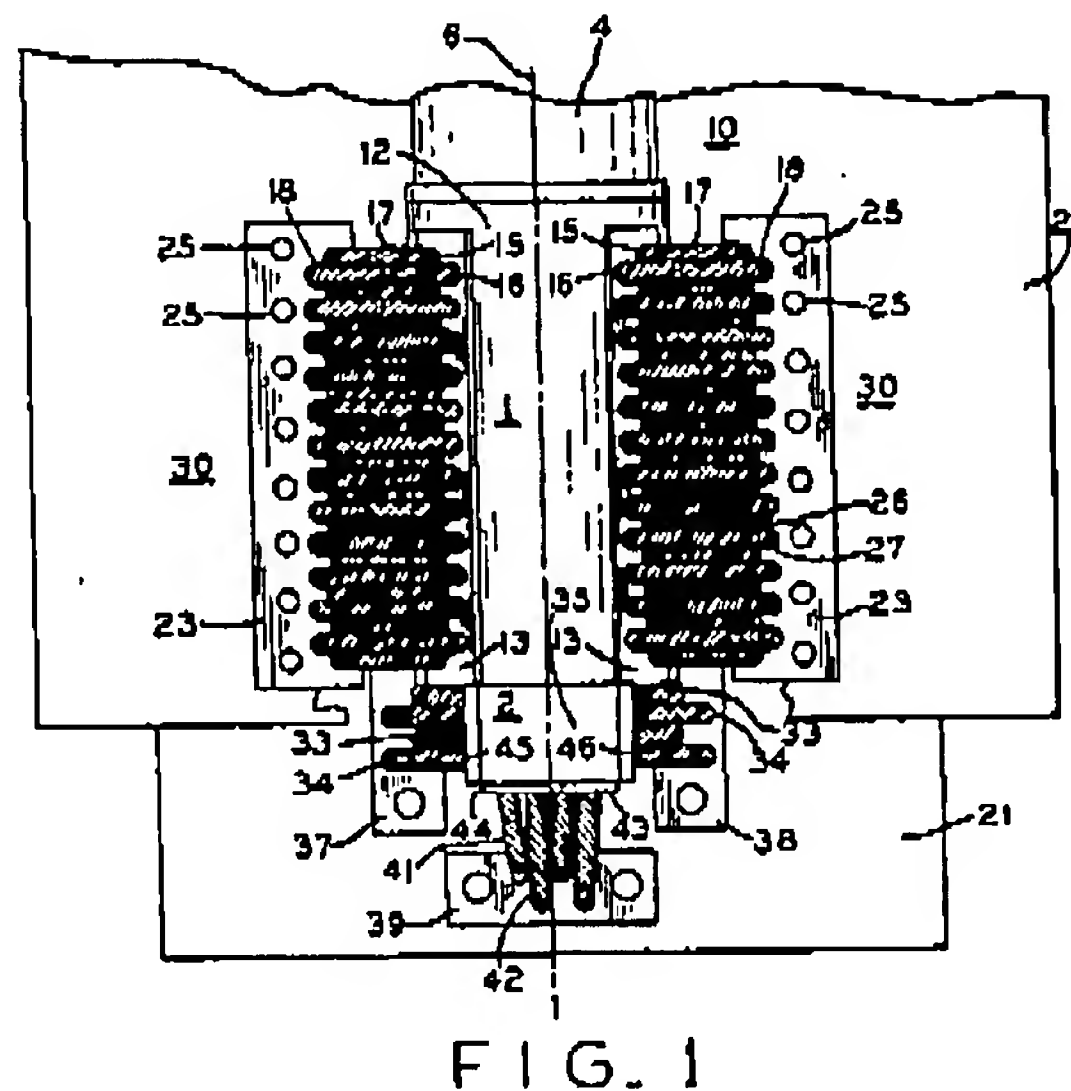


Now when we look to the Goldberg reference we find:

U.S. Patent

June 7, 1994

5,317,879



Here we have clearly illustrated and described a braided conductive strip 64 connected to a copper interface bus 23 (comparable to our cooler block 64). However, the cooler block 23 in Goldberg is mounted directly onto the thermal shield 20. There is no

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teaching of the highly thermally conductive block 66 positioned between the cooler block 64 and the thermal shield 50 as taught and claimed by the present application.

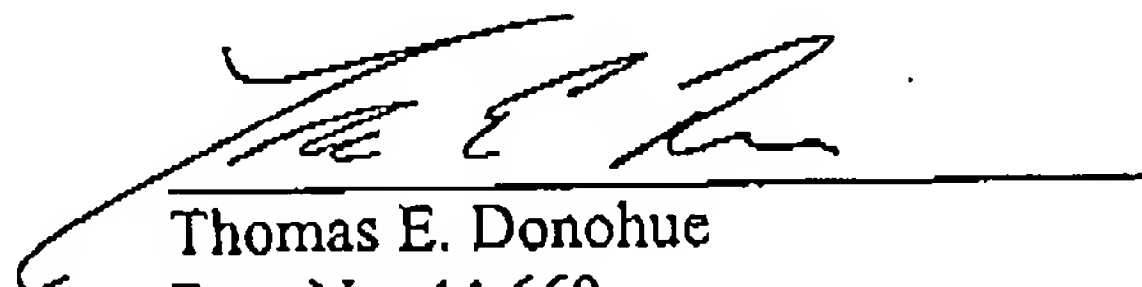
The specification of the Goldberg reference is in complete agreement. The specification in column 3, lines 37-40, of the Goldberg reference clearly indicates that the copper interface bus/cooler block is mounted directly to the thermal shield. Yet the present application clearly requires two independent elements: A cooler block AND a highly thermally conductive block. If they were not independent elements, it would not be possible as claimed for the highly thermally conductive block to be "positioned between the cooler block 64 and an outer thermal shield 50". This is clearly not illustrated, taught, or discussed in the cited reference.

The Applicant, therefore, requests reconsideration.

With this response, it is respectfully submitted that all rejections and objections of record have been overcome and that the case is in condition for allowance.

Should the Examiner have any questions or comments, he is respectfully requested to contact the undersigned.

Respectfully submitted,



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